

JOC302XD5 Series

Rev.A.1.0

DESCRIPTION:

The JOC302XD5 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic DIP5 and SMD package with different lead forming options. With the robust coplanar double mold structure, JOC302XD5 series provide the most stable isolation feature. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors up to 120 V_{AC} peripherals.

MAIN FEATURES

High isolation 5000 VRMS

DC input with random-phase photo triac output

Operating temperature range -55 °C to 100 °C

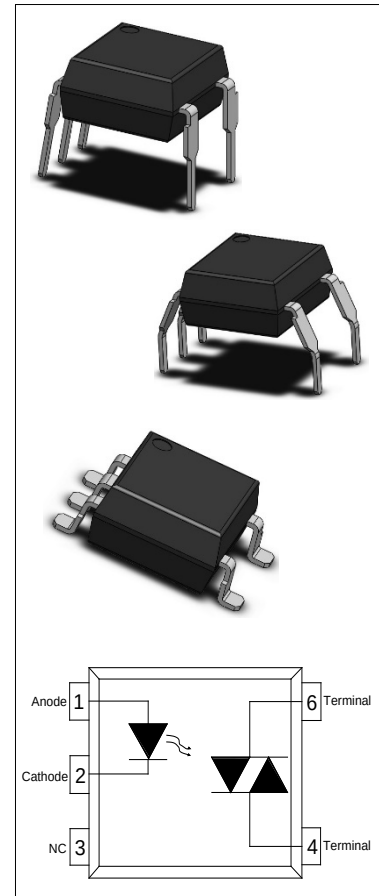
REACH & RoHS compliance

HBM: H3A; MM: M4

CQC approved

VDE approved

UL approved



ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	60	mA
	Reverse Voltage	V_R	6	V
	Junction Temperature	T_j	125	°C
	Input Power Dissipation	P_I	100	mW
	Power Dissipation Derating ($T_a \geq 25^\circ\text{C}$)	$\Delta P_D/^\circ\text{C}$	-1.33	mW/°C
Output	Off-state Output Terminal Voltage	V_{OFF}	400	V
	Peak On-state Current (100µs pulse, 120 pps)	I_{TP}	2	A
	On-state RMS Current	$I_{T(RMS)}$	100	mA
	Peak Repetitive Surge Current ($P_W=10$ ms)	I_{TSM}	1	A

	Junction Temperature	T_j	125	$^{\circ}\text{C}$
	Output Power Dissipation	P_O	250	mW
	Power Dissipation Derating ($T_a \geq 25^{\circ}\text{C}$)	$\Delta P_D/^{\circ}\text{C}$	-3.33	mW/ $^{\circ}\text{C}$
Total Power Dissipation		P_{tot}	350	mW
Isolation Voltage		V_{iso}	5000 ^①	V _{rms}
Operating Temperature		T_{opr}	-55~100	$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-55~125	$^{\circ}\text{C}$
Soldering Temperature		T_{sol}	260 ^②	$^{\circ}\text{C}$

NOTE1: AC for 1minute, R.H.=40~60%

NOTE2: For 10 seconds

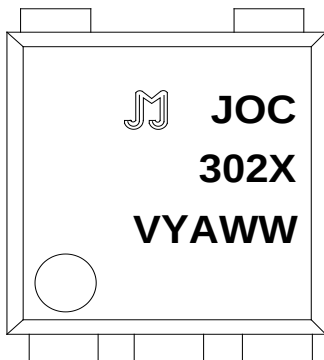
ELECTRICAL CHARACTERISTICS (Temperature=25 $^{\circ}\text{C}$)

Parameter			Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage		V_F	$I_F=10\text{mA}$	-	1.24	1.4	V
	Reverse Current		I_R	$V_R=6\text{V}$	-	-	1	μA
	Input Capacitance		C_{in}	$V=0, f=1\text{kHz}$	-	10	-	pF
Output	Peak Off-state Current, Either Direction		I_{OFF}	$V_{\text{OFF}}=400\text{V}, I_F=0$	-	-	100 ^③	nA
	Peak On-state Voltage, Either Direction		V_{TM}	$I_{\text{TM}}=100\text{mA}$	-	1.8	2.5	V
	Critical Rate of Rise of Off-state voltage		dV/dt	$V_{\text{PEAK}}=400\text{V}, I_F=0$	1000 ^④	-	-	V/ μs
Transfer Characteristics	LED Trigger Current	JOC3021D5	I_{FT}	Terminal Voltage=3V $I_{\text{TM}}=100\text{mA}$	-	-	15	mA
		JOC3022D5			-	-	10	
		JOC3023D5			-	-	5	
	Holding Current		I_H	$I_{\text{TM}}=2\text{mA}, I_F=\text{Rated } I_{\text{FT}}$	-	250	-	μA
	Isolation Resistance		R_{ISO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-	Ω
	Floating Capacitance		C_{IO}	$V=0, f=1\text{MHz}$	-	5	-	pF
	Response Time		t_{on}	$V_D=6\text{V}, R_L=100\Omega, I_F=20\text{mA}$	-	15	50	μs

NOTE3: Test voltage must be applied within dV/dt ratings.

NOTE4: Refer to Fig.14 & Fig.15

ORDERING AND MARKING INFORMATION

MARKING INFORMATION			
		JOC : Company Abbr. 302X : Part Number & Rank V : VDE Option Y : Fiscal Year A : Manufacturing Code WW : Work Week	
ORDERING INFORMATION			
JOC302XD5(Y)(Z)-GV			
JOC – Company Abbr. 302X – Part Number (1/2/3) D5 – DIP5 Package Y – Lead Form Option (M/SL/None) Z – Tape and Reel Option (T1) G – Green Option (G or None) V – VDE Option (V or None)			
Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
None	65 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box =20.8k Units
M	65 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box =20.8k Units
SL(T1)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

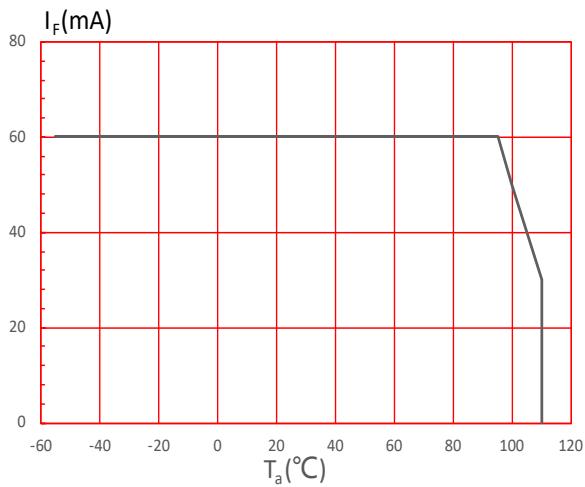


FIG.2: On-state Terminal Current vs. Ambient Temperature

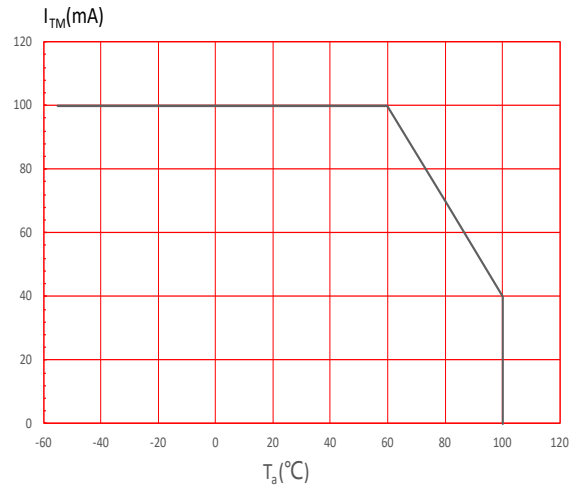


FIG.3: Forward Current vs. Forward Voltage

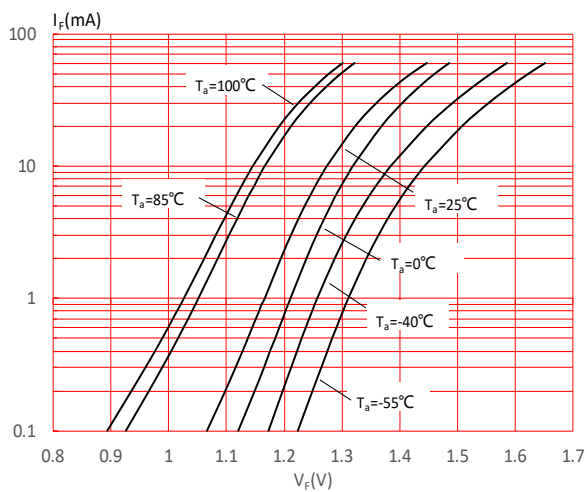


FIG.4: Normalized Off-state Terminal Current vs. Ambient Temperature

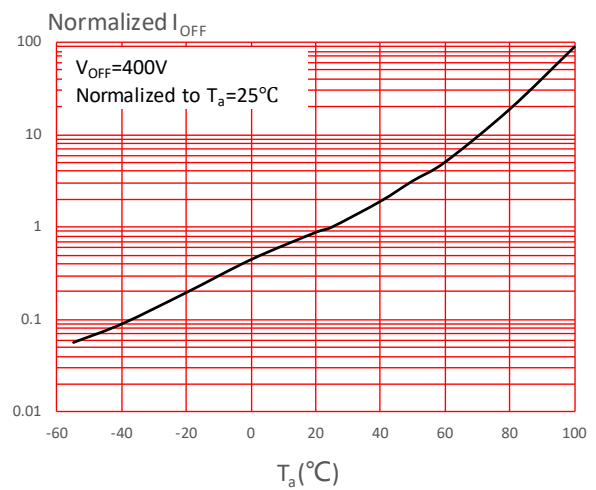


FIG.5: Normalized Off-state Terminal Voltage vs. Ambient Temperature

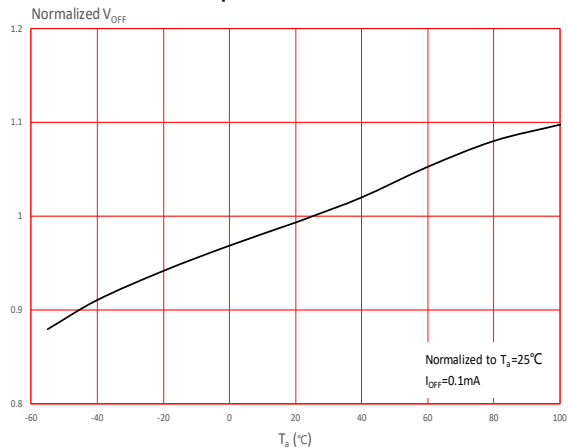


FIG.6: Normalized Trigger Current vs. Ambient Temperature

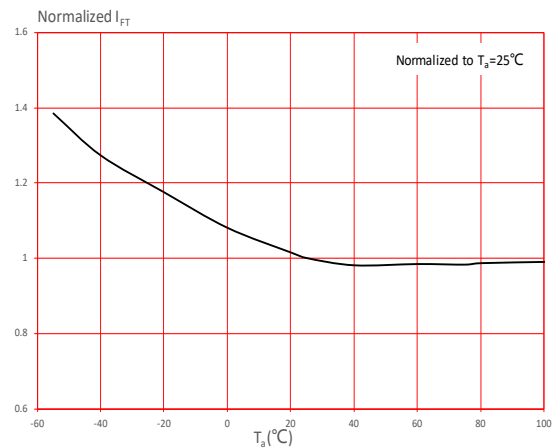
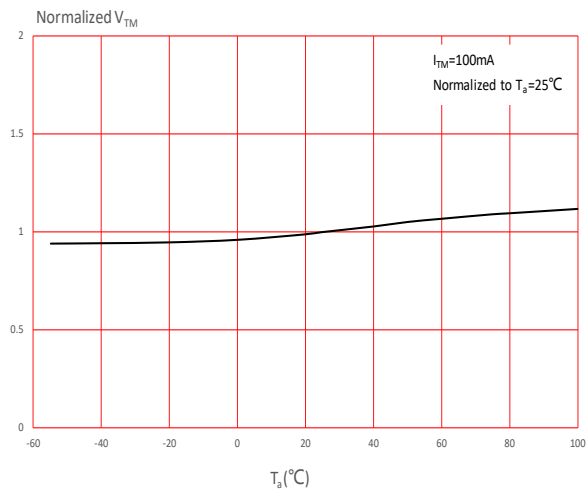
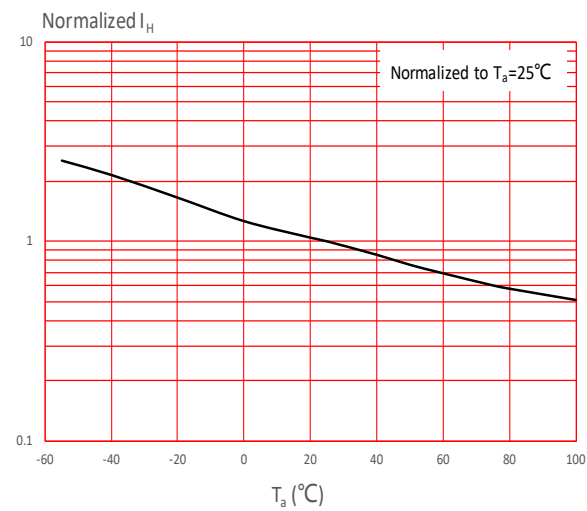
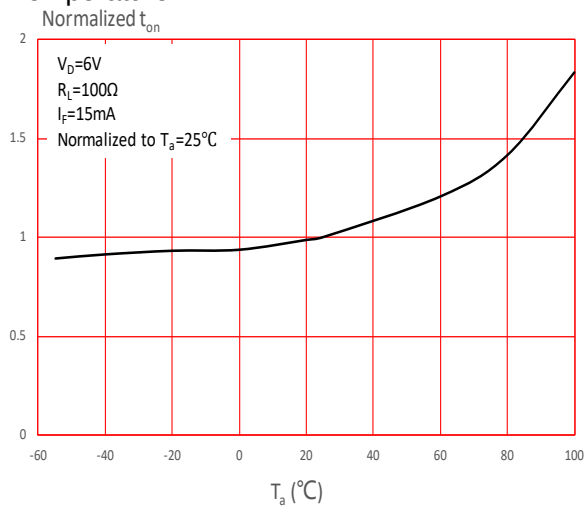
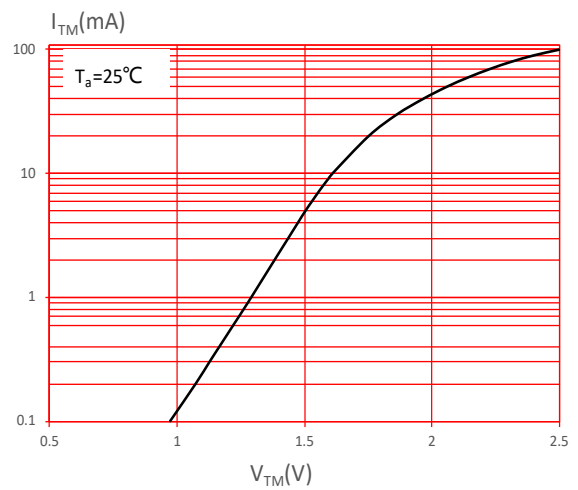
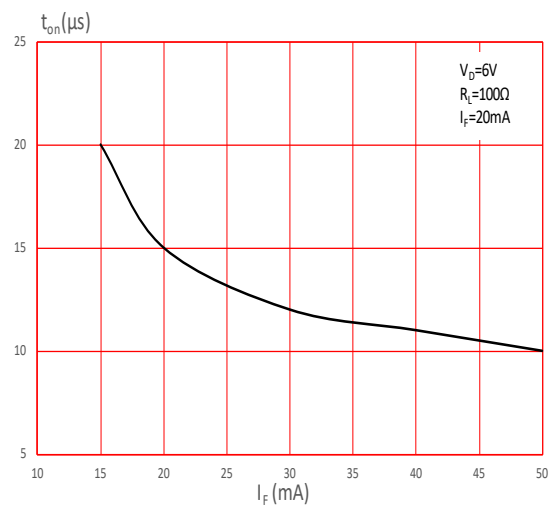


FIG.7: Normalized On-state Terminal Voltage vs. Ambient Temperature**FIG.9:** Normalized Holding Current vs. Ambient Temperature**FIG.11:** Normalized Turn On Time vs. Ambient Temperature**FIG.8:** On-state Terminal Voltage vs. On-state Terminal Current**FIG.10:** Turn On Time vs. Forward Current

TEST CIRCUITS

FIG.12: Test Circuits of Turn On Time

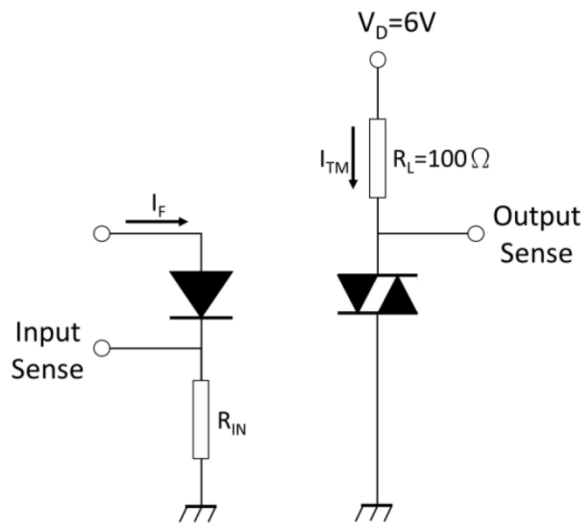


FIG.13: Waveforms of Turn On Time

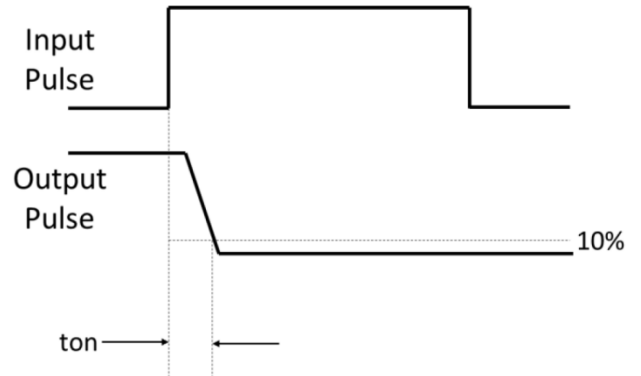


Fig.14: Test Circuits of dV/dt

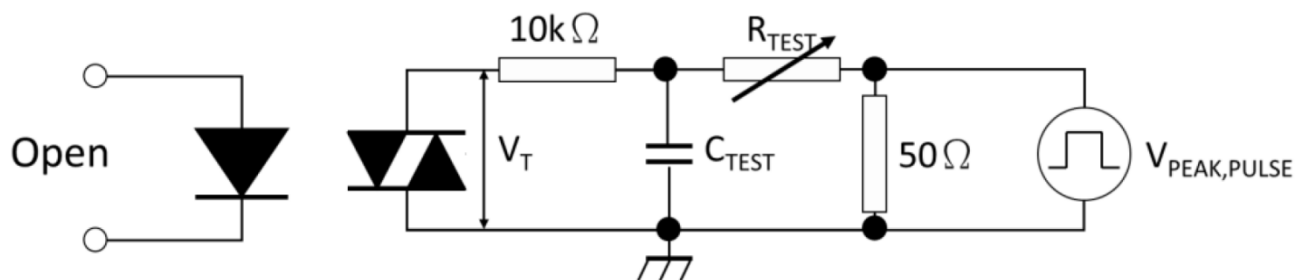
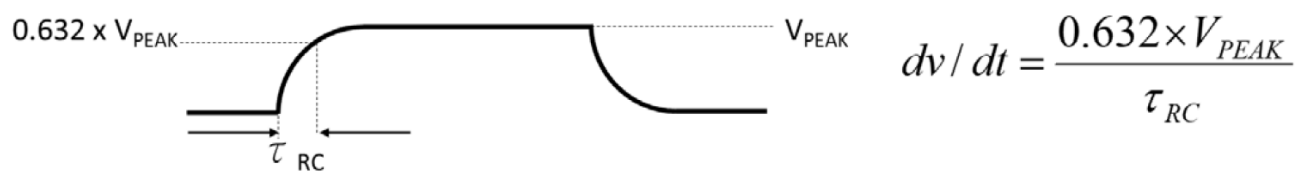
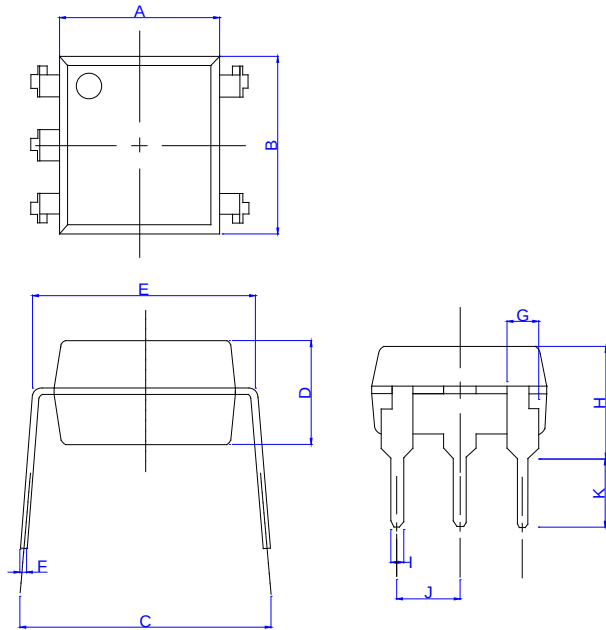


Fig.15: Waveforms of dV/dt



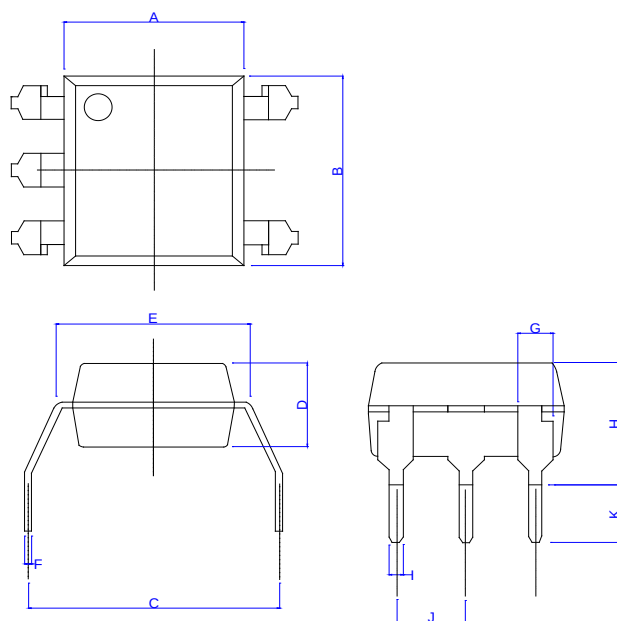
Package Dimension (Unit: mm)

Standard DIP Type:



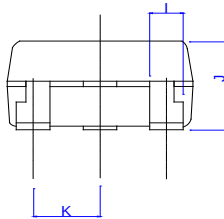
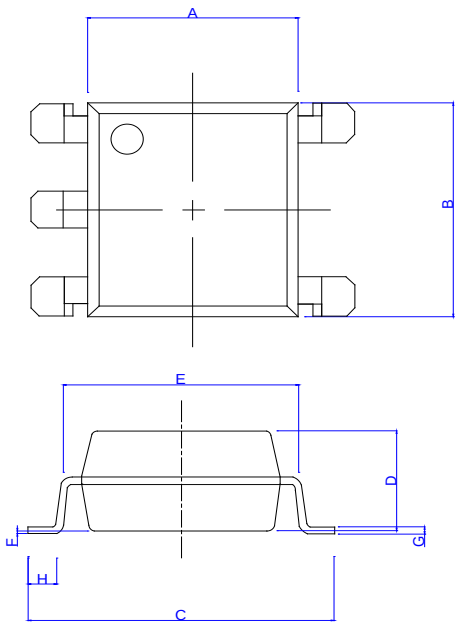
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.237		0.277
B	6.62		7.62	0.262		0.301
C	7.62		10.16	0.301		0.402
D	3.00		4.00	0.119		0.158
E	7.32		7.92	0.289		0.313
F	0.16		0.36	0.006		0.014
G	0.90		1.50	0.036		0.059
H	3.50		4.50	0.138		0.178
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.091		0.110
K	2.40		3.40	0.095		0.134

Option M Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30		6.70	0.249		0.265
B	6.92		7.32	0.274		0.289
C	9.86		10.46	0.390		0.413
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.289		0.313
F		0.25			0.010	
G	1.20		1.40	0.047		0.055
H	4.28		4.88	0.169		0.193
I		0.50			0.020	
J		2.54			0.100	
K	2.20			0.087		

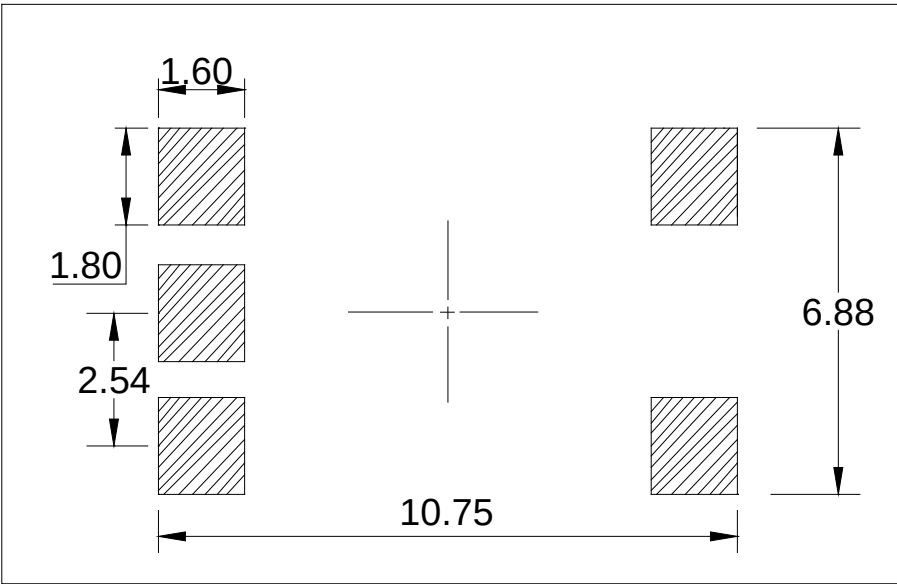
Option SL Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.00		7.00	0.237		0.277
B	6.62		7.62	0.262		0.301
C	9.50		10.00	0.375		0.395
D	3.00		4.00	0.119		0.158
E	7.32		7.92	0.289		0.313
F	0.10		0.65	0.004		0.026
G	0.16		0.36	0.006		0.014
H	1.00		1.40	0.047		0.055
I	0.90		1.50	0.036		0.059
J	3.35		4.35	0.132		0.172
K	2.29		2.79	0.091		0.110

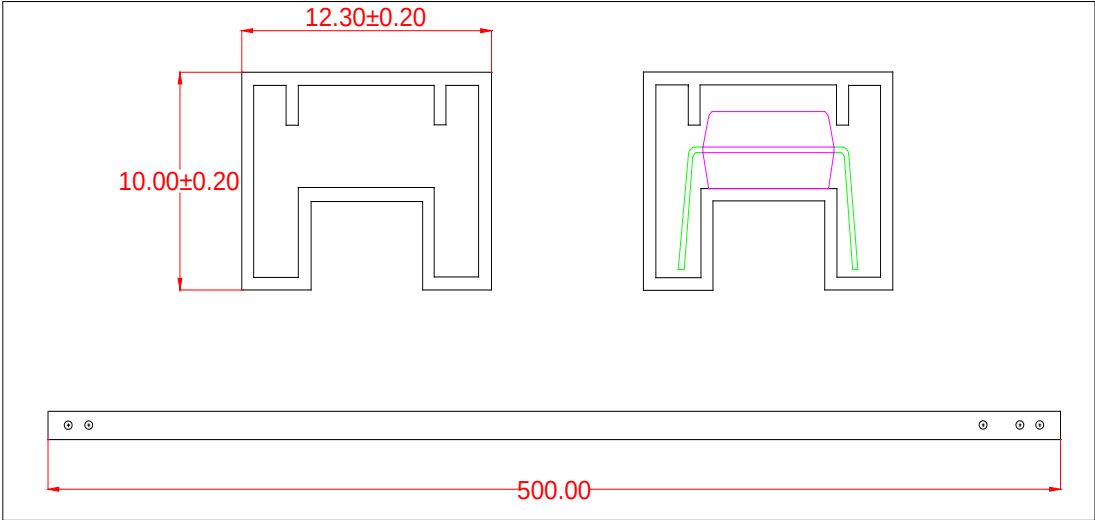
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option SL

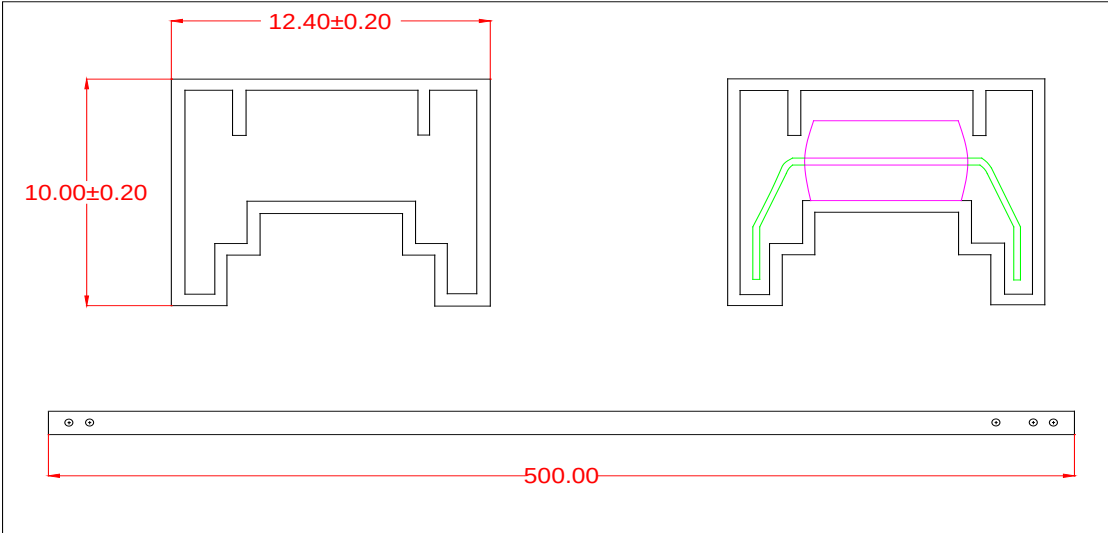


TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP

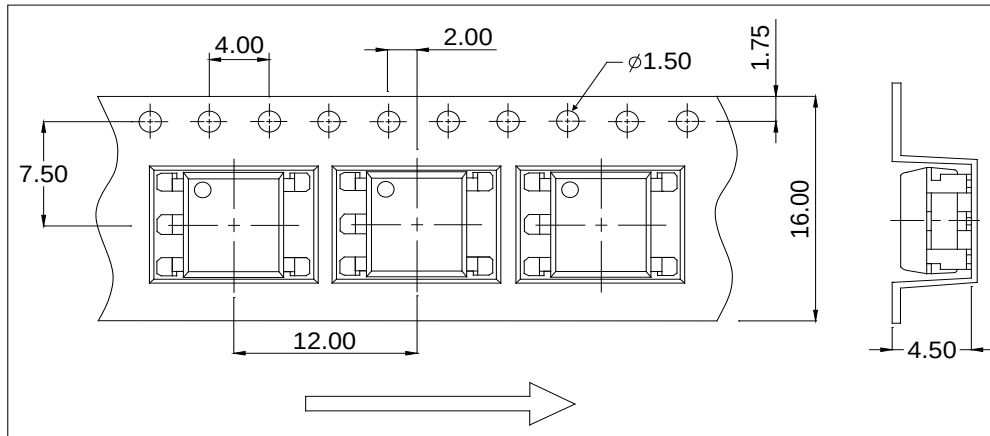


Option M

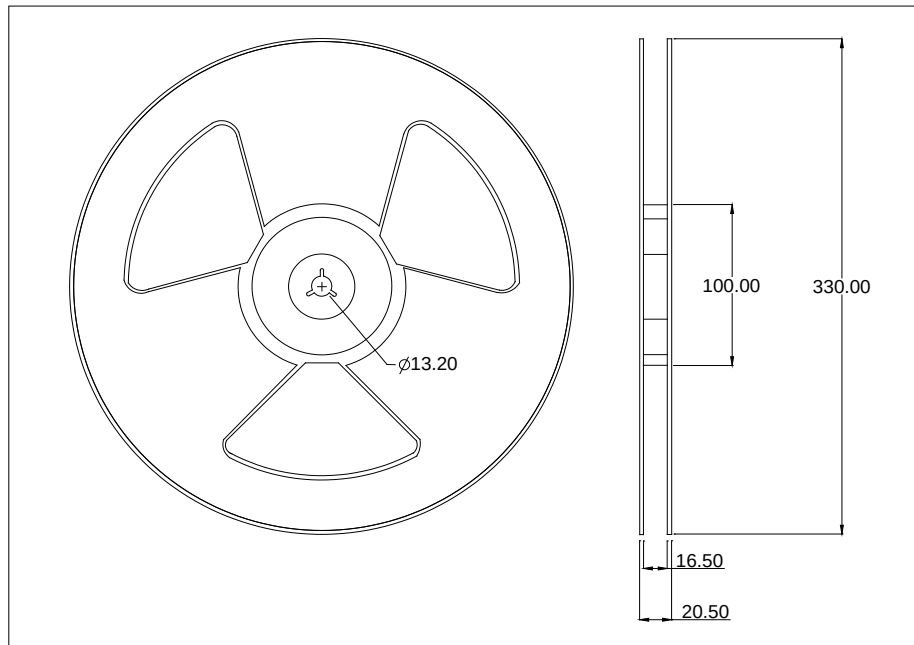


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

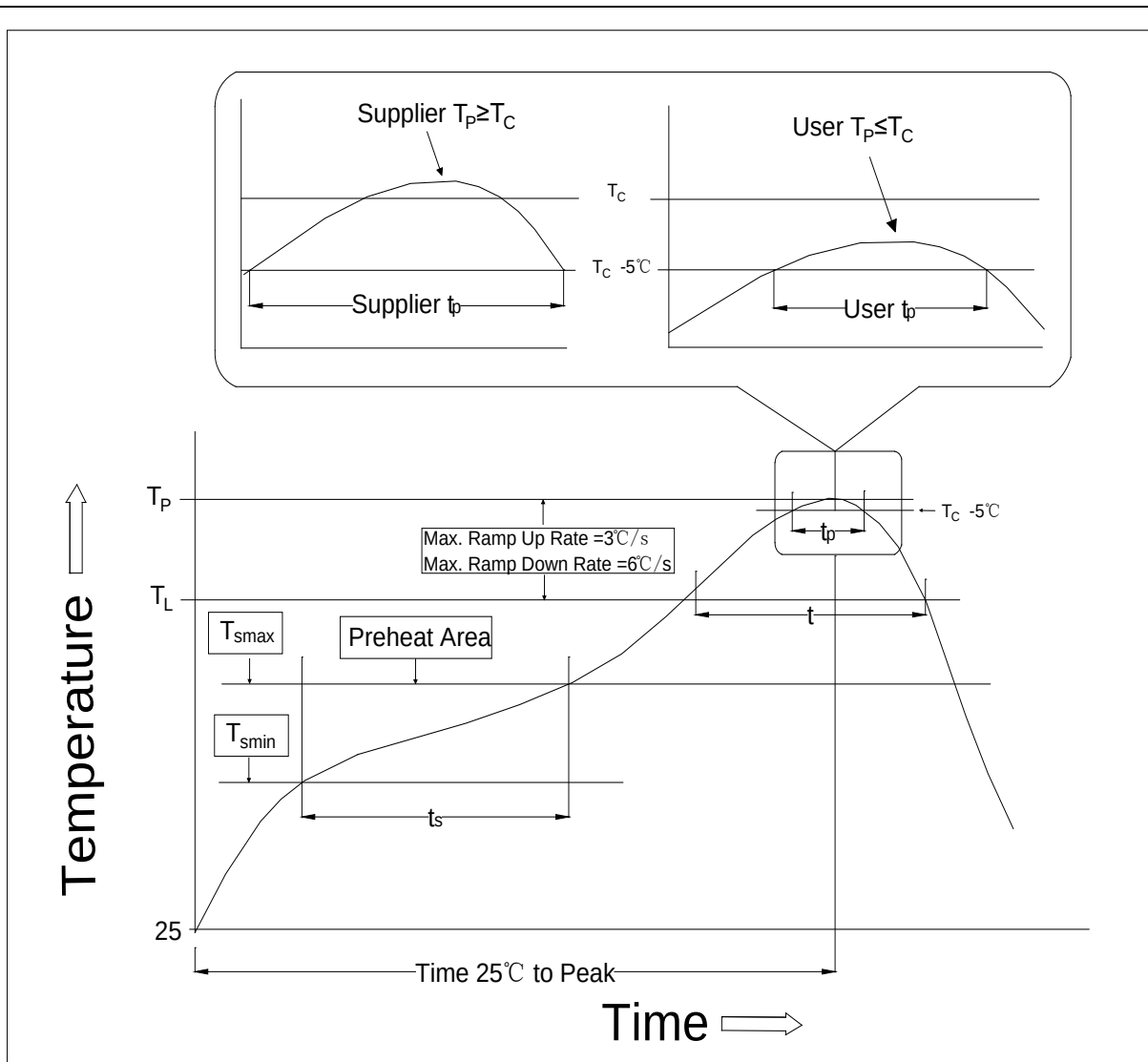
Option SL(T1)

**REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

Option SL

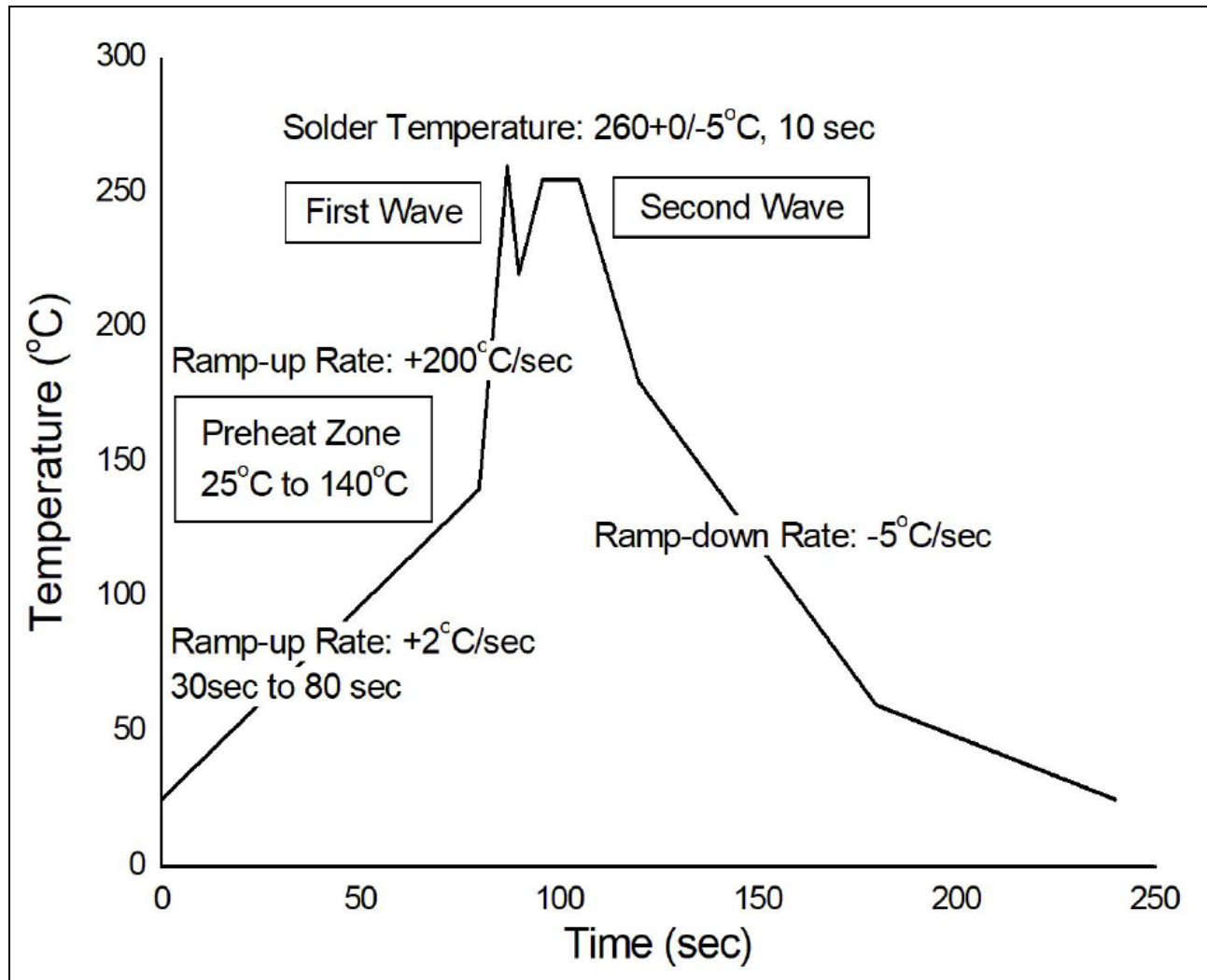


REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	100	150°C
Temperature Max. (T_{smax})	150	200°C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.	3°C/second max.
Liquidus Temperature (T_L)	183°C	217°C
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C+0°C/-5°C	260°C+0°C/-5°C
Time (t_P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON

Soldering Temperature	360±5°C
Soldering Time	3s max.

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